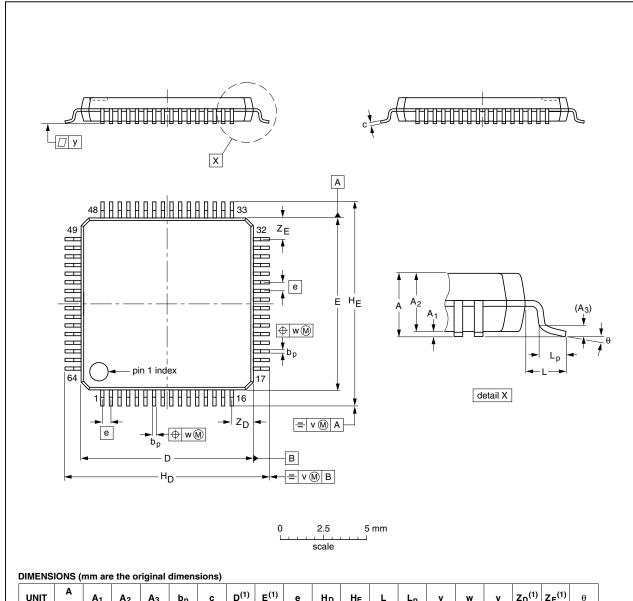


Package outline

LQFP64: plastic low profile quad flat package; 64 leads; body 10 x 10 x 1.4 mm

SOT314-2



UNIT	A max.	A ₁	A ₂	A 3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	H _D	HE	L	Lp	v	w	у	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.6	0.20 0.05	1.45 1.35	0.25	0.27 0.17	0.18 0.12	10.1 9.9	10.1 9.9	0.5	12.15 11.85	- 1	1	0.75 0.45	0.2	0.12	0.1	1.45 1.05	1.45 1.05	7° 0°

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT314-2	136E10	MS-026				00-01-19 03-02-25	





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